Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-43 (canceled)

44. (currently amended) A ~~chip package~~ circuit component comprising:

a substrate;

a semiconductor chip having a front surface and a back surface, wherein said front surface comprises multiple pads, wherein said front surface is on the bottom of said semiconductor chip, and wherein said back surface of said semiconductor chip is on the top of said semiconductor chip;

a machine readable information directly on said back surface of said semiconductor chip, wherein said machine readable information is an identity of product and manufacturer or said machine readable information is a bar code ~~on a back surface of said semiconductor chip~~;

multiple metal bumps directly on a ~~front surface~~ said multiple pads of said semiconductor chip, wherein said multiple metal bumps attach said semiconductor chip to a top surface of said substrate, ~~wherein said front surface is an active device surface of said semiconductor chip~~; and

an optically transparent layer <u>directly</u> over said back surface, wherein said optically

transparent layer covers said identity of product and manufacturer or said bar code, wherein

said identity of product and manufacturer or said bar code is visible <u>and machine readable</u>

through said optically transparent layer.

Claims 45-47 (canceled)

48. (currently amended) The ~~chip package~~ <u>circuit component</u> of claim 44 further comprising

~~a substrate and~~ an underfill ~~material~~ between said front surface and ~~a~~ <u>said</u> top surface of said

substrate, wherein said underfill encloses said multiple <u>metal</u> bumps.

49. (currently amended) The ~~chip package~~ <u>circuit component</u> of claim <u>44</u> ~~45~~ further

comprising multiple balls <u>on</u> ~~under~~ a bottom surface of said substrate.

Claims 50-59 (canceled)

60. (currently amended) The ~~chip package~~ <u>circuit component</u> of claim 44, wherein said

<u>multiple</u> metal <u>bumps comprise</u> ~~bump comprises~~ solder.